

SPECIFICATION FOR LCD MODULE

MODULE NO: YB-TG320240S22A-N-A0

Doc.Version:01

Customer Appro	oval:		
☐ Accept			☐ Reject
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1. Revision History

Sample Version	DOC. Version	DATE	DESCRIPTION		CHANGED BY
A0	00	2019-01-18	SPEC ONLY	First issue	Shien/CFJ
A0	01	2019-04-30	Full spec	First Sample	Shien/CFJ

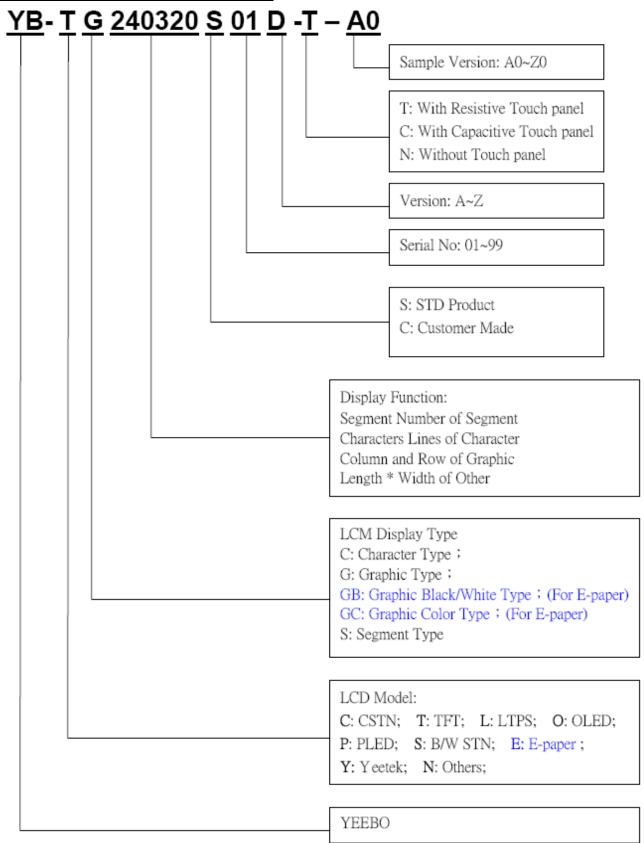


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3. Module Numbering System:



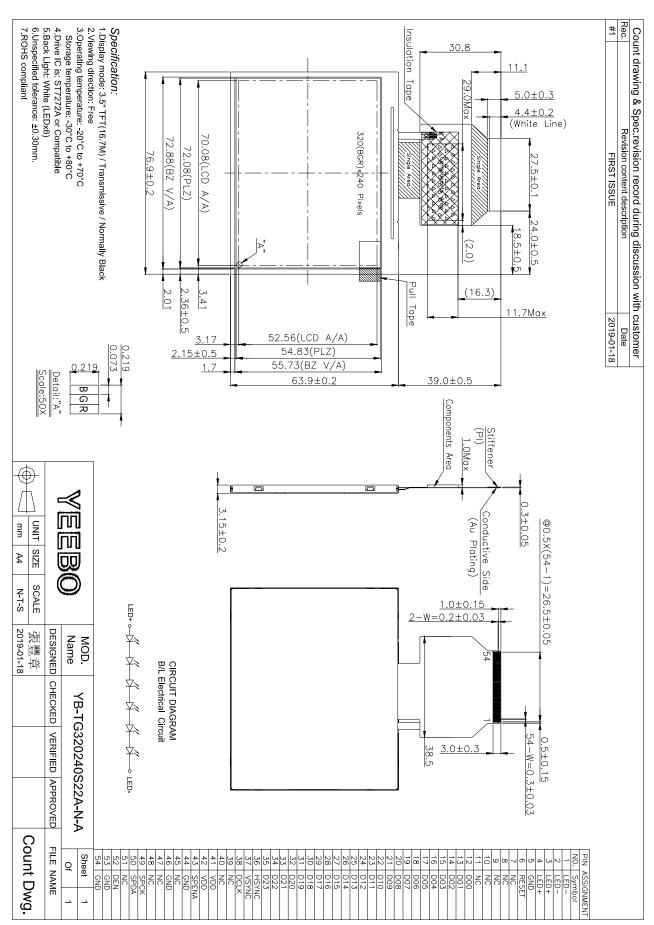


4. General Specification:

ITEM	CONTENTS
Module Size	76.9 (W) * 63.9 (H) * 3.15(T) mm
Module Size(With FPC)	76.9 (W) *102.9 (H) * 3.15(T) mm
Display Size(Diagonal)	3.5 inch
Display Format	320(BGR) * 240 Pixels
Active Area	70.08(W) * 52.56(H) mm
Pixel Pitch	0.219 * 0.219 mm
LCD Type	TFT(262K) / Transmissive/NB
Viewing Direction (Gray Inversion)	FREE
Controller IC	ST7272A
Weight	26.8g



5. LCM drawing:





6. Electrical Characteristics

6-1 Absolute Maximum Ratings

 $(Ta=25^{\circ}C\ VSS=0V)$

Item	Symbol	Min.	Туре	Max.	Unit	Remark
Power Supply Voltage	VDD-VSS	-0.3	•	+4.0	Volt	Note1
Operating Temperature	Topr	-20	-	+70	$^{\circ}\!\mathbb{C}$	-
Storage Temperature	Tstg	-30	ı	+80	$^{\circ}\!\mathbb{C}$	-

Note1: Absolute maximum rating is the limit value beyond which the IC maybe broken. They do not assure operations.

6-2 Operating Conditions

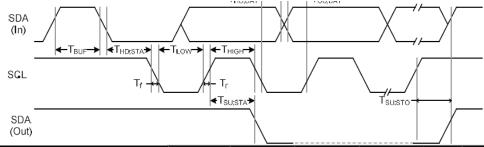
 $(Ta=25^{\circ}C)$

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Power Supply	VDD.VSS	-	3.0	3.3	3.6	Volt
I	V_{IH}	-	0.7 *VDD	-	VDD	V
Input Voltage	V _{IL}	-	0	-	0.3*VDD	V
Power Supply Current for LCM	IDD	VDD=3.3V	-	28.8	38.7	mA



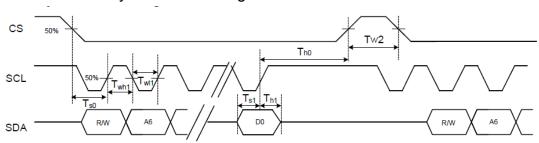
6-3 Timing Characteristics

System Bus Timing for I₂C Interface



Item	Symbol	Min.	Тур.	Max.	Unit	Conditions
SCL Clock Frequency	FSCL	-	-	400	KHz	
SCL Clock Low Period	TLOW	1300	-	-	ns	
SCL Clock High Period	THIGH	600	-	-	ns	
Signal Rise Time	Tr	20+0.1Cb	-	300	ns	
Signal Fall Time	Tf	20+0.1Cb	-	300	ns	
Start Condition Setup Time	TSU;STA	600	-	-	ns	
Start Condition Hold Time	THD;STA	600	-	-	ns	
Data Setup Time	TSU;DAT	100	-	-	ns	
Data Hold Time	THD;DAT	0	-	900	ns	
Setup Time for STOP Condition	TSU;STO	600	-	-	ns	
Bus Free Time Between a STOP	TBUF	100			ns	
and START	IBUF	100	-	-		
Capacitive load represented by		Cb		400	nE	
each bus line		Cb		400	pF	

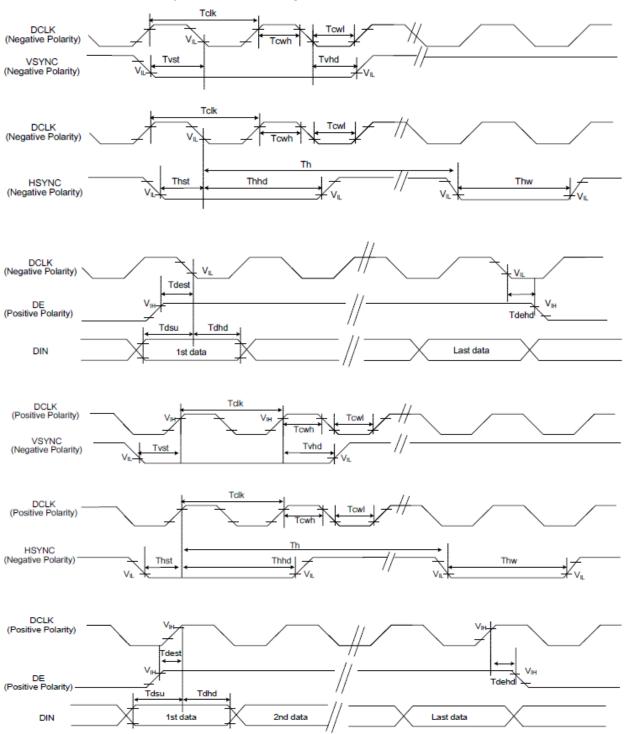
System Bus Timing for 3-Wire SPI Interface



Item	Symbol	Min.	Тур.	Max.	Unit	Conditions
CS Input Setup Time	Ts0	50	-	-	ns	
Serial Data Input Setup Time	Ts1	50	-	-	ns	
CS Input Hold Time	Th0	50	-	-	ns	
Serial Data Input Hold Time	Th1	50	-	-	ns	
SCL Write Pulse High Width	Twh1	50	-	-	ns	
SCL Write Pulse Low Width	Twl1	50	-	-	ns	
SCL Read Pulse High Width	Trh1	300			ns	
SCL Read Pulse Low Width	Trl1	300			ns	
CS Pulse High Width	Tw2	400	-	-	ns	



System Bus Timing for RGB Interface





ltem	Symbol	Min.	Тур.	Max.	Unit	Conditions
CLK Pulse Duty	Tclk	40	50	60	%	
HSYNC Width	Thw	2	-	-	DCLK	
VSYNC Setup Time	Tvst	12	-	-	ns	
VSYNC Hold Time	Tvhd	12	-	-	ns	
HSYNC Setup Time	Thst	12	-	-	ns	
HSYNC Hold Time	Thhd	12	-	-	ns	
Data Setup Time	Tdsu	12	-	-	ns	
Data Hold Time	Tdhd	12	-	-	ns	
DE Setup Time	Tdest	12	-	-	ns	
DE Hold Time	Tdehd	12	-	-	ns	



7. Optical Characteristics:

Itom		Symbol	Conditions	Spe	cificatio	ons	Unit	Note
Iten	Item		Conditions	Min	Тур	Max	Unit	Note
Transmittance (With PL)		T(%)	I	-	6.2	-	-	-
Contrast Ratio		CR	⊕=0 Normal Viewing angle	-	800	-		(1) (2)
Response	time	TR+TF	ı	-	30	40	ms	(1) (3)
	Hor.	Өх+		-	80	-		
Viewing	Θ_{X}	Өх-	CR≧10	-	80	-	doa	_
angle	Ver.	Өу+	$O_{\rm K} = 10$	-	80	-	deg.	-
	vei.	Өу-		-	80	-		

Measuring Condition

1. Measuring surrounding: dark room

2. Ambient temperature: 25±2°C

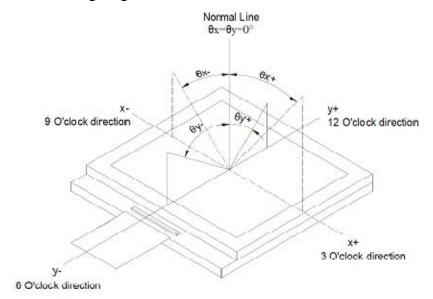
3. 30 min. Warm-up time.

Color of CIE Coordinate:

Item		Symbol	Condition	Min.	Тур.	Max.
	D 1	X		0.580	0.630	0.680
	Red	у		0.302	0.352	0.402
Clamana di aita	C	X	$\theta = \phi = 0$ °	0.325	0.375	0.425
Chromaticity Coordinates	Green	у	y LED Backlight	0.529	0.579	0.629
(Transmissive)	Blue	X	Color Degree	0.092	0.142	0.192
(Transmissive)		у		0.060	0.110	0.160
	3371 .4	X		0.276	0.326	0.376
	White	у		0.295	0.345	0.395



Note (1) Definition of Viewing Angle:

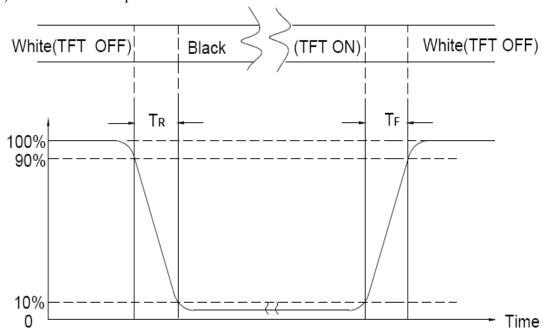


Note (2) Definition of Contrast Ratio(CR): measured at the center point of panel

Contrast ratio (CR)= Photo detector output when LCD is at "White" state

Photo detector output when LCD is at "Black

Note (3) Definition of Response Time: Sum of TR and TF



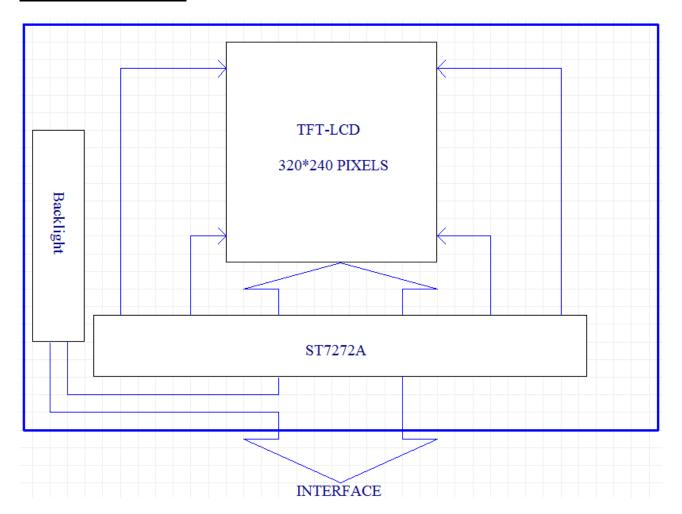


8. Interface Pin Assignment:

No.	Symbol	Function
1~2	LED-	Backlight LED Cathode input pin.
3~4	LED+	Backlight LED Anode input pin.
5	GND	Ground.
6	RESET	System reset pin.
7	NC	No connector.
8	NC	
9	NC	Dummy
10	NC	-Dummy.
11	NC	
12~35	B00~B23	Data Bus.
36	HSYNC	Horizontal Synchronous signal.
37	VSYNC	Vertical Synchronous signal.
38	DCLK	Data clock.
39~40	NC	No connector.
41~42	VCC	Power supply.
43	SPENA	Chip select for serial port use.
44	GND	Ground.
45	NC	No connector.
46	GND	Ground.
47,48	NC	No connector.
49	SPCK	Serial port Clock.
50	SPDA	Serial port Data input/output
51	NC	No connector.
52	DEN	Data enable signal.
53~54	GND	Ground.



9. Block Diagram:





10. Backlight:

- 1. Standard Lamp Styles (Edge Lighting Type):
 The LED chips are distributed over the edge light area of the illumination unit, which gives the less power consumption:
- 2. The Main Advantages of the LED Backlight are as following:
 - 2.1 The brightness of the backlight can simply be adjusted. By a resistor or a potentiometer.
- 3. Data About LED Backlight:

(Ta=25°C)

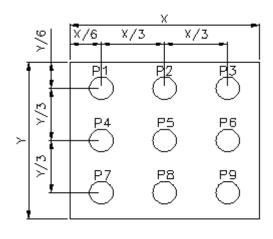
PARAMETER	Sym.	Min.	Тур.	Max.	Unit	Test Condition	Note
Supply Current	Ι	I 20 mA V=19.2V		V=19.2V			
Supply Voltage	V	16.2	19.2	20.4	V		
Luminous Intensity for LCM	IV	400	500	-	cd/m ²	If=20mA	2
Uniformity for LCM	-	70	-	-	%	11-20IIIA	3
Life Time	-	20000	-	-	Hr.		4
Color	White						

NOTE:

- 1. Backlight Only
- 2. Average Luminous Intensity of P1-P9
- 3. Uniformity = Min/Max * 100%
- 4. LED life time defined as follows: The final brightness is at 50% of original brightness

Measured Method: (X*Y: Light Area)

Internal Circuit Diagram



CIRCUIT DIAGRAM

B/L Electrical Circuit



(Effective spatial Distribution)

Using aperture of 1°, distance 50cm



11. Standard Specification for Reliability: 11–1. Standard Specifications for Reliability of LCD Module

No	Item	Description
01	High temperature operation	The sample should be allowed to stand at 70°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
02	Low temperature operation	The sample should be allowed to stand at -20°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
03	High temperature storage	The sample should be allowed to stand at 80°C for 240 hours under no-load condition, and then returning it to normal temperature condition, and allowing it stand for 2 hours.
04	Low temperature storage	The sample should be allowed to stand at -30°C for 240 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours.
05	Moisture storage	The sample should be allowed to stand at 60°C,90%RH MAX for 240 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours.
06	Thermal shock storage	The sample should be allowed to stand the following 10 cycles: -30° C for 30 minutes \rightarrow normal temperature for 5 minutes \rightarrow +80°C for 30 minutes \rightarrow normal temperature for 5 minutes, as one cycle.
07	Packing vibration	Frequency range: 10Hz ~ 55Hz Amplitude of vibration: 1.5mm X,Y,Z 2 hours for each direction. Sweep time: 12 min
08	Packing drop test	According to ISTA 1A 2001.
09	Electrical Static	Air: $\pm 4KV$ 150pF/330 Ω 5 times
	Discharge	Contact: $\pm 2KV \ 150pF/330\Omega \ 5$ time

^{*}Sample size for each test item is 3~5pcs



11 - 2. Testing Conditions and Inspection Criteria

For the final test the testing sample must be stored at room temperature for 24 hours, after the tests listed in Table 11.2, Standard specifications for Reliability have been executed in order to ensure stability.

No	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

11-3. MTBF

MTBF	Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature ($25\pm5^{\circ}$ C), normal humidity ($50\pm10\%$ RH), and in area not exposed to direct sun light.
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12. Specification of Quality Assurance:

12-1. Purpose

This standard for Quality Assurance should affirm the quality of LCD module products to supply to purchaser by YEEBO CORPORATION (Supplier).

12-2. Standard for Quality Test

a. Inspection:

Before delivering, the supplier should take the following tests, and affirm the quality of product.

b. Electro-Optical Characteristics:

According to the individual specification to test the product.

c. Test of Appearance Characteristics:

According to the individual specification to test the product.

d. Test of Reliability Characteristics:

According to the definition of reliability on the specification for testing products.

e. Delivery Test:

Before delivering, the supplier should take the delivery test.

- (i) Test method: According to ISO2859-1.General Inspection Level
 ☐ take a single time.
- (ii) The defects classify of AQL as following:

Major defect: AQL = 0.65 Minor defect: AQL = 2.5 Total defects: AQL = 2.5

12-3. Non- conforming Analysis & Deal With Manners

- a. Non- conforming Analysis:
 - (i) Purchaser should supply the detail data of non- conforming sample and the non-conforming.
 - (ii) After accepting the detail data from purchaser, the analysis of non- conforming should be finished in two weeks.
 - (iii) If supplier can not finish analysis on time, must announce purchaser before 3 days.
- b. Disposition of non- conforming:
 - (i) If find any product defect of supplier during assembly time, supplier must change the good product for every defect after recognition.
 - (ii) Both supplier and customer should analyze the reason and discuss the disposition of non-conforming when the reason of nonconforming is not sure.

12-4. Agreement items

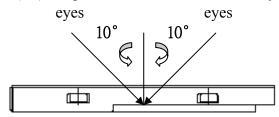
Both sides should discuss together when the following problems happen.

- a. There is any problem of standard of quality assurance, and both sides should think that must be modified
- b. There is any argument item which does not record in the standard of quality assurance.
- c. Any other special problem.

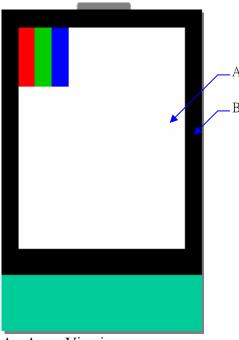


12-5. Standard of The Product Appearance Test

- a. Manner of appearance test:
- (i) The test must be under $20W \times 2$ or 40W fluorescent light, and the distance of view must be at $30\pm5cm$.
 - (ii) When test the model of transmissive product must add the reflective plate.
 - (iii)The test direction is base on around 10° of vertical line.
 - (iiii)Temperature: 25±5°C Humidity: 60±10%RH



(iv) Definition of area:



- A. Area: Viewing area.
- B. Area: Out of viewing area. (Outside viewing area)
- b. Basic principle:
 - (i) It will accord to the AQL when the standard can not be described.
 - (ii) The sample of the lowest acceptable quality level must be discussed by both supplier and customer when any dispute happened.
 - (iii) Must add new item on time when it is necessary.
 - c. Standard of inspection: (Unit: mm)



12-6. Inspection specification

Defect out of viewing area can be neglected.

NO	Item	Criterion				
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Flicker 				
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	 2.1 White and black or color spots on display ≤ 0.25mm, no more than Five spots. 2.2 Densely spaced: No more than three spots within 3mm. 2.3 Not visible through 5% ND filter 				2.5
	LCD and Touch Panel black spots,	3.1 Round type: As follow $\Phi = (X+Y)/2$ $X \leftarrow \qquad $	() () () ()	Size(mm) $Φ \le 0.10$ $0.10 < Φ \le 0.20$ $0.20 < Φ \le 0.25$ $0.25 < Φ \le 0.30$ 0.30 < Φ than two	Acceptable Q'ty Accept no dense 2 2 1 0 spots within 3mm.	2.5
03	white spots, contamination (non – display)	→ L + _	Length(mm) L≤3.0 L≤2.5	ing) Width(mm) $W \le 0.02$ $0.02 < W \le 0.05$ $0.03 < W \le 0.08$ $0.08 < W$	Acceptable Q'ty Accept no dense 2 Rejection o lines within 3mm.	2.5



NO	Item	Criterion			
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction	Size Φ ($\Phi \le 0$ $0.20 < \Phi \le 0$ $0.50 < \Phi \le 0$ $1.00 < 0$ $0.50 < 0$.20 Accep ≤0.50 ≤1.00 <Φ	table Q'ty t no dense 3 2 0 3
05	Scratches	Follow NO.3 -2 Line Type.			
06	Mura	Not visible through 5% ND	filter in 50% gray	· .	2.5
07	Chipped glass	k: Seal width t: Glat L: Electrode pad length 6.1 General glass chip: 6.1.1 Chip on panel surface a surface z : Chip thickness z : Chip thickness z : Not z : Not z : Not z : Not z : Unit: mm z : Chip there are 2 or more chip z : Chip thickness z : Chip thickness z : Chip thickness z : Chip thickness z : Not z : Chip thickness z : Not z : Chip thickness z : Not z : Chip thickness z : Chip t	and crack between width over viewing area exceed 1/3k ps, x is the total le width over viewing area exceed 1/3k	x: Chip length $x \le 1/8a$ $x \le 1/8a$ ength of each chiral $x \le 1/8a$ $x \le 1/8a$ $x \le 1/8a$ $x \le 1/8a$	2.5 p



NO	Item	Criterion	AQL
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length 7.2 Protrusion over terminal: 7.2.1 Chip on electrode pad:	
		y: Chip width x: Chip length z: Chip thickness	
		$y \le 0.5 \text{mm} \qquad x \le 1/8 \text{a} \qquad 0 < z \le t$	
08	Glass crack	Non-conductive portion:	2.5
		y: Chip width x: Chip length z: Chip thickness	
		$y \le L \qquad x \le 1/8a \qquad 0 < z \le t$	
		 If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. If the product will be heat sealed by the customer, the alignment mark must mot be damaged. 7.2.3 Substrate protuberance and internal crack y: width x: length y≤1/3L X≤a 	



NO	Item	Criterion	AQL
09	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
10	Backlight elements	 9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong. 	2.5 2.5 0.65
11	Bezel	Bezel must comply with product specifications.	2.5
12	PCB、COB	 11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart. 	2.5 2.5 2.5 2.5 0.65
13	FPC	12.1 FPC terminal damage \leq 1/2 FPC terminal width and can not affect the function, we judge accept. 12.2 FPC alignment hole damage \leq 1/2 alignment area and can not affect the function, we judge accept.	2.5
14	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle.13.2 No short circuits in components on PCB or FPC.	2.5 0.65



NO	Item	Criterion A			
NO	Item	Symbols: x: Chip length k: Seal width length L: Electrode pad leng 14.1 General glass ch 14.1.1 Chip on panel	y: Chip width z: Chip thickness t: Touch Panel Total thickness a: LCD side		
		z: Chip thickness	y: Chip width $\leq 1/2$ k and not over	x: Chip length	
15	Touch Panel Chipped	Z≦t	viewing area	x≤1/8a	2.5
13	glass	 ○ Unit: mm ○ If there are 2 or m 14.1.2 Corner crack: 	nore chips, x is the total	length of each chip	
		z: Chip thickness	y: Chip width	x: Chip length	
		z≦t	≤1/2 k and not over viewing area	x≤1/8a	
		⊙ Unit: mm⊙ If there are 2 or m	nore chips, x is the total	length of each chip	



NO	Item	Criterion	AQL	
16	Touch Panel(Fish eye, dent and bubble on film)		2.5	
17	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion($\leq 2.5\%$), it is acceptable.	2.5	
18	Touch Panel Linearity	Less than 2.5% is acceptable.		
19	LCD Ripple	Touch the touch panel, can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g	2.5	
20	General appearance	 19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet. 	0.65 0.65 0.65 0.65	



13. Handling Precaution:

13-1 Handling of LCM

- Don't give external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance. Must not lick and swallow. when the liquid is attach to your hand, skin, cloth etc. Wash it out thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads,the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

13-2 Storage

- Store in an ambient temperature of 25±10°C, and in a relative humidity of 50±10%RH. Don't expose to sunlight or fluorescent light.
- Storage in a clean environment, free from dust, active gas, and solvent.
- Store in anti-static electricity container.
- Store without any physical load.

13-3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: No higher than 280±10°C and less than 3 sec during Hand soldering.
- Rewiring: no more than 2 times.

14. Guarantee:

Our products could meet requirements of the environment. YB's RoHS is introduce European Union Directive 2011/65/EU (ROHS) Requirements and Update.